ART FILM - fab1

0.062
BOTH
2 OZ (EXT) /1 OZ (INT)
MIX
BOTH
6 LAYERS
0.005/0.005
3
8
10

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.

PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET COMPLIANT WITH LEAD FREE PROCESS.

GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP, SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.

THICK COPPER.
Holes requiring plating, see hole chart, to have 1 oz. (0.0014) min. thk min.
With RMA Flux, 0.0005" +/- 0.0003" thick min.
All exposed areas as coated, no active fluxes are acceptable.

Plate with RoHS compliant, immersion silver preferred, immersion tin or Sn/Ag/Cu, board must be registered by vendor's identification code (etch or white non-conductive ink). If required, silk-screen legend(s) with white non-conductive epoxy ink. Location optional.

PC BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.

PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.


TOP SIDE TOP SILKSCREEN (WHITE)
TOP SIDE SOLDERMASK
LAYER #1 TOP SIDE TRACES (2 OZ)
5 MILS
LAYER #2 GROUND PLANE (1 OZ)
5 MILS
LAYER #3 INNER TRACES (1 OZ)
.0625/.005 35 MILS NOM.*
LAYER #4 INNER TRACES (1 OZ)
5 MILS
LAYER #5 POWER PLANE (1 OZ)
5 MILS
LAYER #6 BOTTOM SIDE TRACES (2 OZ)
#ADJUSTABLE DIMENSION WITH CONSTRAINTS GIVEN
BOTTOM SIDE SOLDERMASK
BOTTOM SIDE TOP SILKSCREEN (WHITE)

VIEW X-X
SCALE = NONE

DRILL CHART: TOP TO BOTTOM
ALL UNITS ARE IN MILS

<table>
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<tr>
<th>FIGURE</th>
<th>SIZE</th>
<th>TOLERANCE</th>
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<th>QTY</th>
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